

Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.

Description

The Super Bright Yellow source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

SUBMINIATURE SOLID STATE LAMP



1. All dimensions are in millimeters (inches).
2. Tolerance is 0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	I _v (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	
GHB-GW20-Y	SUPER BRIGHTYELLOW (hGaAlP)	WATER CLEAR	110	700	20°

Note:

- 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25 C

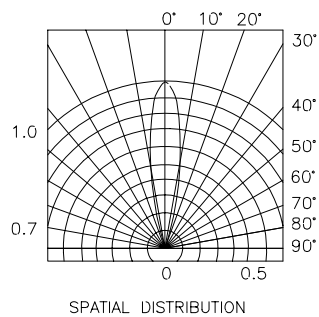
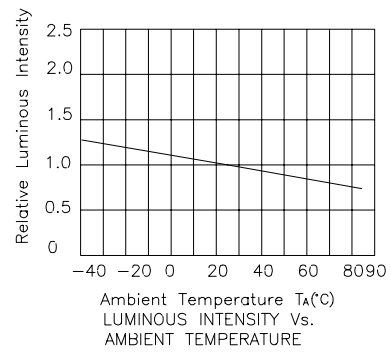
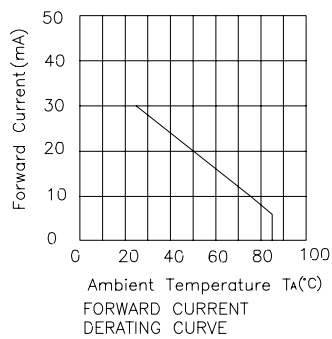
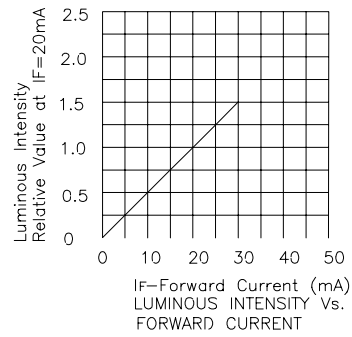
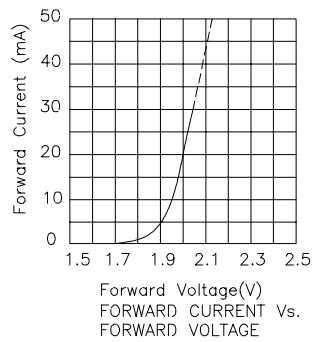
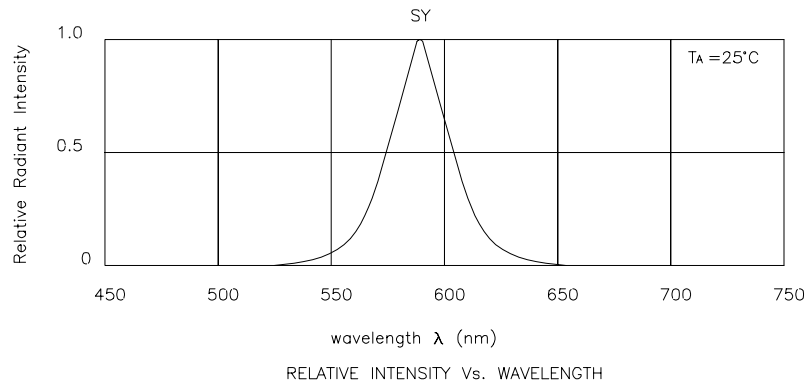
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
peak	Peak Wavelength	Super Bright Yellow	590		nm	I _F =20mA
D	Dominant Wavelength	Super Bright Yellow	588		nm	I _F =20mA
1/2	Spectral Line Half-width	Super Bright Yellow	28		nm	I _F =20mA
C	Capacitance	Super Bright Yellow	25		pF	V _F =0V,f=1MHz
V _F	Forward Voltage	Super Bright Yellow	2.0	2.5	V	I _F =20mA
I _R	Reverse Current	Super Bright Yellow		10	uA	V _R = 5V

Absolute Maximum Ratings at T_A=25 C

Parameter	Super Bright Yellow	Units
Power dissipation	125	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40 C To +85 C	

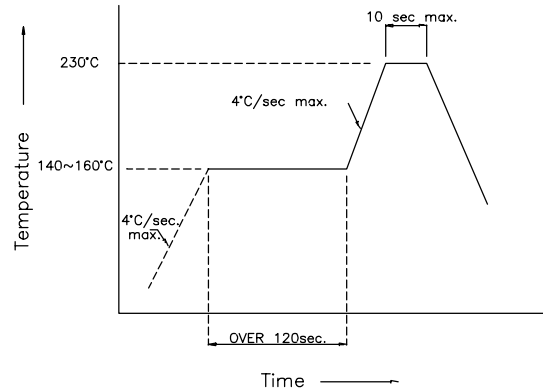
Note:

- 1/10 Duty Cycle, 0.1ms Pulse Width.

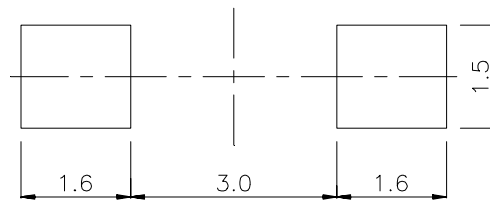


SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

